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(54) **DISPLAY PANEL AND MANUFACTURING METHOD THEREOF**

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ABSTRACT

A display panel and a manufacturing method thereof are provided. The display panel includes a substrate, a first metal layer, a first insulating layer, and a dam layer arranged in a stack. The first metal layer includes a first signal wiring. A light-emitting unit is bonded to the first signal wiring through a solder paste in a first opening of the first insulating layer and a second opening of the dam layer. A side of the dam layer away from the substrate is higher than or equal to a side of the solder paste away from the substrate. This application can prevent the solder paste from overflowing.

